

Material Content Data Sheet

Sales Product Name	IM12S90EA2	**Issued**	28. March 2025
MA#	MA006150707		
Package	PG-MDIP-24-63	**Weight:**	6918.48 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	6.694	0.10	0.10	968	968
chip_2	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
chip_3	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
chip_4	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
chip_5	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
chip_6	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
chip_7	inorganic material	siliconcarbide	409-21-2	1.924	0.03	0.03	278	278
leadframe	inorganic material	phosphorus	7723-14-0	0.390	0.01		56	
	non noble metal	iron	7439-89-6	1.300	0.02		188	
	non noble metal	copper	7440-50-8	1298.097	18.76	18.79	187627	187871
wire	noble metal	gold	7440-57-5	0.609	0.01		88	
	non noble metal	aluminium	7429-90-5	28.789	0.42	0.43	4161	4249
encapsulation	organic material	carbon black	1333-86-4	30.895	0.45		4466	
	plastics	epoxy resin	-	386.187	5.58		55820	
	inorganic material	silicondioxide	60676-86-0	3444.791	49.77	55.80	497912	558198
leadfinish	non noble metal	tin	7440-31-5	41.697	0.60	0.60	6027	6027
plating	non noble metal	nickel	7440-02-0	2.741	0.04	0.04	396	396
solder	non noble metal	antimony	7440-36-0	0.293			42	
	noble metal	silver	7440-22-4	0.734	0.01		106	
	non noble metal	tin	7440-31-5	1.908	0.03	0.04	276	424
glue	inorganic material	amorphous silica	7631-86-9	0.263			38	
	plastics	acrylic resin	-	0.592	0.01		85	
	noble metal	silver	7440-22-4	1.313	0.02	0.03	190	313
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		83	
	inorganic	manganesedioxide	1313-13-9	0.658	0.01	0.02	95	236

	material							
pcb metal	non noble metal	copper	7440-50-8	21.446	0.31	0.31	3100	3100
pcb plastic	miscellaneous	miscellaneous	-	26.649	0.39		3852	
	inorganic material	silicondioxide	60676-86-0	42.639	0.62		6163	
	organic material	Poly[phenylglycidylether-coformaldehyde]	28064-14-4	50.634	0.73		7319	
	inorganic material	glass fibre	-	146.572	2.12	3.86	21186	38520
pcb plating	noble metal	gold	7440-57-5	0.066			10	
	non noble metal	nickel	7440-02-0	3.029	0.04	0.04	438	448
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	7.862	0.11		1136	
	inorganic material	aluminum nitride	24304-00-5	697.271	10.08	10.19	100784	101920
dcb metal	non noble metal	copper	7440-50-8	661.840	9.57	9.57	95662	95662
deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com